

### Silicon Carbide Power Schottky Diode Chip

#### Features

- 650 V Schottky rectifier
- 250 °C maximum operating temperature
- Temperature independent switching behavior
- Superior surge current capability
- Positive temperature coefficient of  $V_{\text{F}}$
- Extremely fast switching speeds
- Superior figure of merit Q<sub>C</sub>/I<sub>F</sub>



#### Maximum Ratings at T<sub>j</sub> = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V <sub>RRM</sub>		650	V
Continuous forward current	l <sub>F</sub>	T <sub>C</sub> ≤ 235 °C	1	А
RMS forward current	I <sub>F(RMS)</sub>	T <sub>C</sub> ≤ 235 °C	2	А
Operating and storage temperature	$T_{j}$ , $T_{stg}$		-55 to 250	°C

#### Electrical Characteristics at T<sub>j</sub> = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions -		Values		l lmit	
				min.	typ.	max.	Unit
Diode forward voltage	VF	$I_F = 1 \text{ A}, T_j = 25 \text{ °C}$		1.5		V	
		I <sub>F</sub> = 1 A, I <sub>j</sub> = 210 °C		2.3			
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 650 V, T <sub>j</sub> = 25 °C		0.03	5	μΑ	
		V <sub>R</sub> = 650 V, T <sub>j</sub> = 250 °C		1.7	20		
Total capacitive charge	Qc	$ _{F} \leq  _{F,MAX}$	V <sub>R</sub> = 400 V		7		nC
Switching time	t <sub>s</sub>	$T_i = 210 \text{ eV}$	V <sub>R</sub> = 400 V		< 17		ns
Total capacitance		V <sub>R</sub> = 1 V, f = 1 MHz, T <sub>j</sub> = 25 °C V <sub>R</sub> = 400 V, f = 1 MHz, T <sub>j</sub> = 25 °C		76		pF	
	С			12			
		V <sub>R</sub> = 800 V, f = 1 MH:	z, T <sub>i</sub> = 25 °C		11		
Thermal Characteristics							

Thermal resistance, junction - case	R <sub>thJC</sub>	Assuming TO-276 package	3.55	°C/W

\*For chip size and metallization, please refer to the mechanical datasheet (must have a non-disclosure agreement with GeneSiC Semiconductor).

# **Electrical Datasheet\***

## GB01SHT06-CAU



Figure 1: Typical Forward Characteristics



Figure 3: Typical Junction Capacitance vs Reverse Voltage Characteristics



Figure 2: Typical Reverse Characteristics





Revision History					
Date	Revision	Comments	Supersedes		
2012/04/03	0	Initial release			

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### **SPICE Model Parameters**

Copy the following code into a SPICE software program for simulation of the GB01SHT06-CAU device.

```
*
     MODEL OF GeneSiC Semiconductor Inc.
*
*
     $Revision: 1.0
                               $
*
     $Date: 05-SEP-2013
                               $
*
*
    GeneSiC Semiconductor Inc.
*
    43670 Trade Center Place Ste. 155
*
    Dulles, VA 20166
*
    httphttp://www.genesicsemi.com/index.php/sic-products/schottky
*
*
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     ALL RIGHTS RESERVED
* These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
* OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
* TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
* PARTICULAR PURPOSE."
* Models accurate up to 2 times rated drain current.
* Start of GB01SHT06-CAU SPICE Model
.SUBCKT GB01SHT06 ANODE KATHODE
D1 ANODE KATHODE GB01SHT06 25C; Call the Schottky Diode Model
D2 ANODE KATHODE GB01SHT06 PIN; Call the PiN Diode Model
.MODEL GB01SHT06 25C D
+ IS
      3.57E-18
                        RS
                                    0.49751
+ TRS1
                        TRS2
         0.0057
                                    2.40E-05
+ N
         1
                         IKF
                                    322
+ EG
         1.2
                        XTI
                                    3
        9.12E-11
                        VJ
                                   0.371817384
+ CJO
         1.527759838
                                    0.5
+ M
                        FC
+ TT
         1.00E-10
                         BV
                                    800
+ IBV
         1.00E-03
                          VPK
                                    650
                                    SiC Schottky
+ IAVE
         1
                          TYPE
+ MFG GeneSiC Semiconductor
.MODEL GB01SHT06 PIN D
+ IS 5.73E-11
                        RS
                                   0.72994
+ N
          5
                         IKF
                                    800
+ EG
                                    -14
         3.23
                         XTI
+ FC
         0.5
                         TT
                                    Ω
+ BV
         800
                         IBV
                                   1.00E-03
         650
+ VPK
                         IAVE
                                   1
+ TYPE
         SiC PiN
.ENDS
* End of GB01SHT06-CAU SPICE Model
```